Single Inverter

The NL17SG04 MiniGate[™] is an advanced high-speed CMOS Inverter in ultra-small footprint.

The NL17SG04 input structures provides protection when voltages up to 4.6 V are applied.

Features

- Wide Operating V_{CC} Range: 0.9 V to 3.6 V
- High Speed: $t_{PD} = 2.3$ ns (Typ) at $V_{CC} = 3.0$ V, $C_L = 15$ pF
- Low Power Dissipation: $I_{CC} = 0.5 \mu A$ (Max) at $T_A = 25^{\circ}C$
- 4.6 V Overvoltage Tolerant (OVT) Input Pins
- Ultra-Small Packages
- These are Pb-Free and Halide-Free Devices

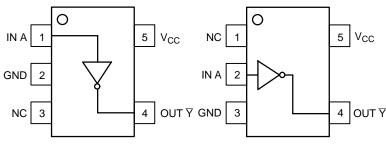


Figure 1. SOT-953 (Top Thru View)

Figure 2. SC-88A (Top View)

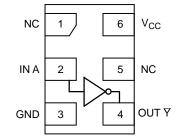


Figure 3. UDFN (Top View)

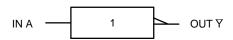


Figure 4. Logic Symbol



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MARKING DIAGRAMS



SOT-953 CASE 527AE





UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.45 x 1.0 CASE 517AQ





SC-88A DF SUFFIX CASE 419A



M = Date Code*

= Pb–Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT					
	SOT-953	SC-88A	UDFN6		
1	IN A	NC	NC		
2	GND	IN A	IN A		
3	NC	GND	GND		
4	OUT ₹	OUT ₹	OUT ₹		
5	V _{CC}	V _{CC}	NC		
6			V _{CC}		

FUNCTION TABLE

A Input	₹ Output
L	Н
Н	L

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +5.5	V
V _{IN}	DC Input Voltage		-0.5 to +4.6	V
V _{OUT}	DC Output Voltage	Output at High or Low State Power–Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} +0.5 -0.5 to +4.6	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA
lok	DC Output Diode Current	V _{OUT} < GND	-20	mA
I _{OUT}	DC Output Source/Sink Current		±20	mA
I _{CC}	DC Supply Current per Supply Pin		±20	mA
I _{GND}	DC Ground Current per Ground Pin		±20	mA
T _{STG}	Storage Temperature Range		−65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	>2000 >100	V
I _{LATCHUP}	Latchup Performance Above V _{CC} an	d Below GND at 125°C (Note 4)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

Tested to EIA/JESD22-A114-A.

Tested to EIA/JESD22-A115-A.

- 4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics			Max	Unit
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V_{IN}	Digital Input Voltage		0.0	3.6	V
V _{OUT}	Output Voltage Output at High or Low Power–Down Mode (V _{CC}	State = 0 V)	0.0 0.0	V _{CC} 3.6	V
T _A	Operating Temperature Range		- 55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fail Rate $V_{CC} = 3.3 \text{ V} \pm$	0.3 V	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

					T _A =	25°C	T _A -55°C to	, =) +125°C				
Symbol	Parameter	C	onditions	V _{CC} (V)	Min	Max	Min	Max	Unit			
V _{IH}	High-Level Input			0.9	V _{CC}		V _{CC}		V			
	Voltage			1.1 to 1.3	0.7xV _{CC}		0.7xV _{CC}					
				1.4 to 1.6	0.65xV _{CC}		0.65xV _{CC}					
				1.65 to 1.95	0.65xV _{CC}		0.65xV _{CC}					
				2.3 to 2.7	1.7		1.7					
				3.0 to 3.6	2.0		2.0					
V _{IL}	Low-Level Input			0.9		GND		GND	V			
	Voltage			1.1 to 1.3		0.3xV _{CC}		0.3xV _{CC}				
				1.4 to 1.6		0.35xV _{CC}		0.35xV _{CC}				
				1.65 to 1.95		0.35xV _{CC}		0.35xV _{CC}				
				2.3 to 2.7		0.7		0.7				
				3.0 to 3.6		0.8		0.8				
V _{OH} High-Level		V _{IN} =	$I_{OH} = -20 \mu A$	0.9	0.75		0.75		V			
	Output Voltage	Output voltage	Output voltage	Output Voltage	V _{IH} or V _{IL}	I _{OH} = -0.3 mA	1.1 to 1.3	0.75xV _{CC}		0.75xV _{CC}		
			I _{OH} = -1.7 mA	1.4 to 1.6	0.75xV _{CC}		0.75xV _{CC}					
					I _{OH} = -3.0 mA	1.65 to 1.95	Vcc-0.45		V _{CC} -0.4 5			
			I _{OH} = -4.0 mA	2.3 to 2.7	2.0		2.0					
			I _{OH} = -8.0 mA	3.0 to 3.6	2.48		2.48					
V_{OL}	Low-Level	V _{IN} =	I _{OL} = 20 μA	0.9		0.1		0.1	V			
	Output Voltage	V _{IH} or V _{IL}	I _{OL} = 0.3 mA	1.1 to 1.3		0.25xV _{CC}		0.25xV _{CC}				
			I _{OL} = 1.7 mA	1.4 to 1.6		0.25xV _{CC}		0.25xV _{CC}				
		I _{OL} = 3.0 mA	1.65 to 1.95		0.45		0.45					
			I _{OL} = 4.0 mA	2.3 to 2.7		0.4		0.4				
			I _{OL} = 8.0 mA	3.0 to 3.6		0.4		0.4				
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 3.6 V		0 to 3.6		±0.1		±1.0	μΑ			
I _{CC}	Quiescent Supply Current	V _{IN} =	V _{CC} or GND	3.6		0.5		10.0	μΑ			

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS Input $t_r = t_f = 3.0 \text{ ns}$

Symbol	Parameter	Test Condition	V _{CC} (V)	,	T _A = 25° C		T _A -55°C to	= +125°C												
			Min	Тур	Max	Min	Max	Unit												
t _{PLH} ,	Propagation Delay,	C _L = 10 pF,	0.9	-	10.0	13.3	-	17.0	ns											
t _{PHL}	- A to Y	$R_L = 1 M\Omega$	1.1 to 1.3	-	8.7	11.2	-	14.0												
			1.4 to 1.6	-	4.9	8.5	-	10.0												
			1.65 to 1.95	-	3.8	6.2	-	6.7												
			2.3 to 2.7	-	2.6	3.9	-	4.4												
			3.0 to 3.6	-	2.1	3.1	-	3.7												
		$C_L = 15 \text{ pF},$ $R_L = 1 \text{ M}\Omega$	0.9	-	11.55	13.7	-	19.7	ns											
			1.1 to 1.3	-	7.2	10.8	-	15.6												
			1.4 to 1.6	-	5.4	9.3	-	11.2												
			1.65 to 1.95	-	4.2	6.9	-	7.1												
								1		2.3 to 2.7	-	2.8	4.4	-	5.0					
			3.0 to 3.6	-	2.3	3.4	-	3.9												
		C _L = 30 pF,	0.9	-	16.85	18.9	-	22.3	ns											
		$R_L = 1 M\Omega$	1.1 to 1.3	-	10.2	13.4	-	17.5												
			1.4 to 1.6	-	7.4	13.1	-	15.9												
														1.65 to 1.95	-	5.6	9.2	-	9.6	
															2.3 to 2.7	-	3.7	5.7	-	6.1
			3.0 to 3.6	-	2.9	4.4	-	4.8												
C _{IN}	Input Capacitance		0 to 3.6		3	-	-	-	pF											
C _{PD}	Power Dissipation Capacitance (Note 5)	f = 10 MHz	0.9 to 3.6	-	4	<u>-</u>	-	-	pF											

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC} \cdot C_{PD}$ is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

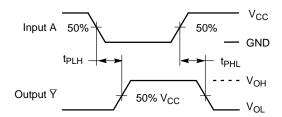
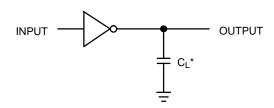


Figure 5. Switching Waveforms



*Includes all probe and jig capacitance.
A 1–MHz square input wave is recommended for propagation delay tests.

Figure 6. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NL17SG04P5T5G	SOT-953 (Pb-Free)	8000 / Tape & Reel
NL17SG04DFT2G	SC-88A (Pb-Free)	3000 / Tape & Reel
NL17SG04AMUTCG	UDFN6 1.45x1 mm (Pb-Free)	3000 / Tape & Reel
NL17SG04CMUTCG	UDFN6 1x1 mm (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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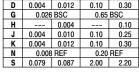
SC-88A (SC-70-5/SOT-353) CASE 419A-02 **ISSUE L**

DATE 17 JAN 2013



- TIES:
 DIMENSIONING AND TOLERANCING
 PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 419A-01 OBSOLETE. NEW STANDARD
- 419A-02.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
9	0.070	0.087	2 00	2 20



GENERIC MARKING DIAGRAM*



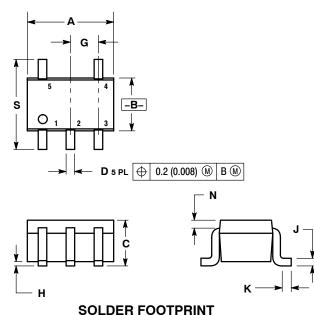
XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



0.0197			
			0.65 0.025
0.40		-	0.65 0.025
	1.9 0.0748	SCALE 20:1	$\left(\frac{\text{mm}}{\text{inches}}\right)$

0.50

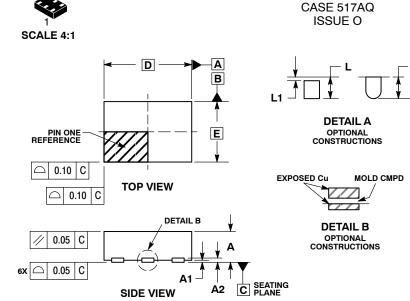
STYLE 1:	STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR	STYLE 3:	STYLE 4:	STYLE 5:
PIN 1. BASE		PIN 1. ANODE 1	PIN 1. SOURCE 1	PIN 1. CATHODE
2. EMITTER		2. N/C	2. DRAIN 1/2	2. COMMON ANODE
3. BASE		3. ANODE 2	3. SOURCE 1	3. CATHODE 2
4. COLLECTOR		4. CATHODE 2	4. GATE 1	4. CATHODE 3
4. COLLECTOR5. COLLECTOR	4. COLLECTOR	4. CATHODE 2	4. GATE 1	4. CATHODE 3
	5. CATHODE	5. CATHODE 1	5. GATE 2	5. CATHODE 4

5. COLLECTOR	5. CATHODE	5. CATHODE 1	5. GATE 2	5. CATHODE 4
STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 5. COLLECTOR 2/BASE 1	STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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DESCRIPTION:	SC-88A (SC-70-5/SOT-35	· · · · · · · · · · · · · · · · · · ·	PAGE 1 OF 1		

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6X L

6X b

0.10 | C | A | B

0.05 C NOTE 3



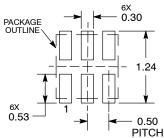
DATE 15 MAY 2008

UDFN6, 1.45x1.0, 0.5P

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00 0.05		
A2	0.07 REF		
b	0.20	0.30	
D	1.45 BSC		
Е	1.00 BSC		
Ф	0.50 BSC		
L	0.30	0.40	
L1	0.15		

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

BOTTOM VIEW

XM

= Specific Device Code

= Date Code

е

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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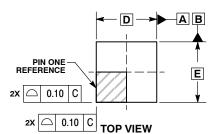
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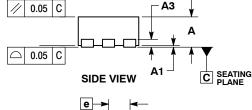


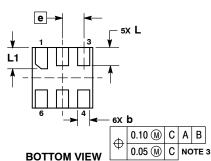


UDFN6, 1x1, 0.35P CASE 517BX **ISSUE O**

DATE 18 MAY 2011





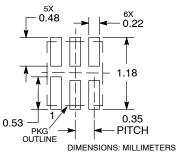


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.20 MM FROM TERMINAL TIP. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45	0.55	
A1	0.00 0.05		
A3	0.13 REF		
b	0.12	0.22	
D	1.00 BSC		
E	1.00 BSC		
е	0.35 BSC		
L	0.25	0.35	
L1	0.30 0.40		

RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code

M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

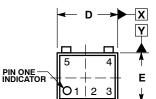
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DESCRIPTION:	UDFN6, 1x1, 0.35P		PAGE 1 OF 1

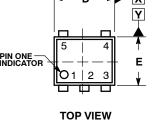
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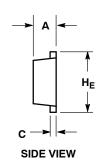


CASE 527AE **ISSUE E**

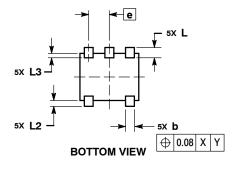
DATE 02 AUG 2011



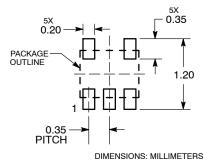




SOT-953



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE
- MINIMUM THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.34	0.37	0.40
b	0.10	0.15	0.20
С	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
е	0.35 BSC		
HE	0.95	1.00	1.05
L	0.175 REF		
L2	0.05	0.10	0.15
L3			0.15

GENERIC MARKING DIAGRAM*



= Specific Device Code = Month Code

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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